

Abstract of the Disclosure

There are provided glass-ceramics having an ultra low thermal expansion property and super flat surface capable of coping with lithography for the next generation LSI and component parts for semiconductor equipment such as masks, optical reflecting mirrors, wafer stages and reticle stages and various precision parts using such glass-ceramics. Glass-ceramics of the invention have an average linear thermal expansion coefficient within a range of $0.0 \pm 0.2 \times 10^{-7}/^{\circ}\text{C}$ within a temperature range from 0°C to 50°C , have difference between the maximum value and the minimum value of $\Delta L/L$ of 10×10^{-7} or below, and comprise SiO_2 , Al_2O_3 and P_2O_5 with the total amount thereof in mass % being within a range from 86.0% to 89.0%.